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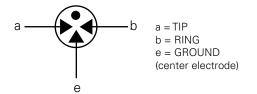
SL1021A/B Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
91	E128662

3 Electrode GDT Graphical Symbol



Features

- RoHS compliant
- Low insertion loss
- Excellent response to fast rising transients
- Ultra low capacitance
- 10KA (A suffix devices) / 20KA (B suffix devices) surge capability tested with 8/20µs pulse as defined by IEC 61000-4-5
- Available with thermal failsafe option (add 'F' suffix to part number)

Applications

SL1021:

- Broadband equipment
- ADSL equipment
- XDSL equipment
- Satellite and CATV equipment
- Splitters
- General telecom
 equipment

- Telecom network interfaces
- Telephone line cards
- Repeaters
- Modems
- Line test equipment

Description

GDT circuit protection devices dissipate electrical surge energy safely within a contained plasma gas. Commonly used to help protect sensitive telecom and networking equipment and lines, GDTs protect from damage that may result from lightning strikes and equipment switching operations.

RoHS

The Littelfuse GDT series described in this document are available in a variety of leaded and surface mount forms and offered with and without optional fail-safe clip. Please refer to the electrical specifications, dimension and packaging options section of this document for additional information.

SL1021A/B Series:

SL1021A/B series GDTs are designed to offer high levels of performance on fast rising transients in the range of $100V/\mu$ S to $1KV/\mu$ S, which are those most likely created by induced lightning disturbances.

These devices feature ultra low capacitance (typically 1.5pF or less) and are extremely robust with SL1021A devices able to divert a 10,000 Amp pulse without destruction, and SL1021B suffix devices able to divert a 20,000 Amp pulse without destruction.

These series offer optimized internal geometry which provide low insertion loss at high frequencies, ideal for the protection of broadband and other high speed transmission equipment.

Product Characteristics

	L
Materials	Dull Tin Plate 17.5 ± 12.5 Microns. with ceramic insulator
Product Marking	'LF' mark, voltage& date code: SL1021A - Red /White text SL1021B - Blue /White text
Glow to arc transition current	~ 1Amp
Glow Voltage	~60-200 Volts
Storage and Operation Temperature	-40 to +90°C
Transverse Voltage (Delay Time)	< 0.2µSec (Tested to ITU-T Rec. K.12)
Arc Voltage	~10 to 35 Volts
Holdover Voltage	<150mS (Tested to ITU-T Rec. K.12)

Gas Discharge Tubes SL1021A/B Series



Electrical Characteristics

Device Specifications (at 25°C)					Life Ratings																							
Part Number		C Volta 00V/Se		DC Voltage 100 V/	DC Voltage 1kV//	/oltage tance Resistance Current Curr 1kV/ @1Mbz) 50Hz 8/20µ	Surge Current 8/20µSec	Single Surge 1	Surge Life 10/1000																			
Number	MIN	TYP	MAX	μSec.	μSec.		MIN		x10 ¹	8/20µSec1	10/350µSec¹	µSecx300¹																
SL1021B075	60	75	90		650		>10 ¹⁰ O				4kA ²																	
SL1021A090 SL1021B090	72	90	108				(at 50V)				5kA ³																	
SL1021A145 SL1021B145	116	145	174	500	600																							
SL1021A150 SL1021B150	120	150	180																									
SL1021A200	150	200	250				50																					
SL1021A230 SL1021B230	184	230	276	450	650 700 <1.5pf 850 900	700 <1.5pF																						
SL1021A250 SL1021B250	200	250	300	500				<1.5pF	_ <1.5pF	<1.5pF																		
SL1021A260 SL1021B260	210	260	310	550			< 1.5pr				<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF	<1.5pF		10Amps	10kA ² 20kA ³
SL1021A300 SL1021B300	240	300	360	650					>10 ¹⁰ Ω (at 100V)		20101	20101	2.5kA ² 5kA ³															
SL1021A350 SL1021B350	280	350	420	700																								
SL1021A400 SL1021B400	320	400	480	850 95	050	050																						
SL1021A420 SL1021B420	345	420	500		950	950																						
SL1021A450 SL1021B450	360	450	540	900	1000																							
SL1021A500 SL1021B500	400	500	600	950	1100																							
SL1021A600	480	600	720	1000	1200																							

NOTES:

1. Total current through centre electrode, tested in accordance with ITU-T Rec K.12

2. SL1021A series

3. SL1021B series

Additional Information





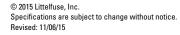
Resources SL1021B





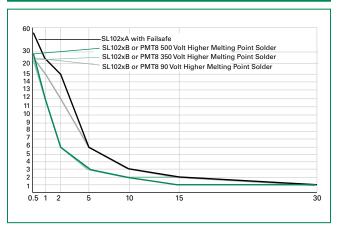
Samples

SL1021B

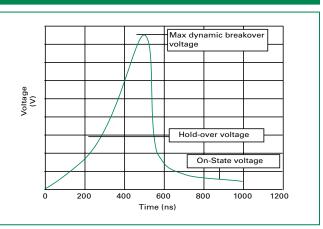




Time vs. Current for Failsafe

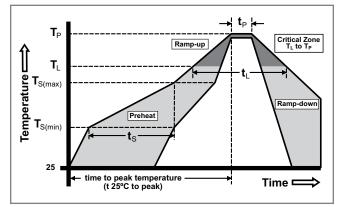


Voltage vs. Time Characteristic



Soldering Parameters - Reflow Soldering (Surface Mount Devices)

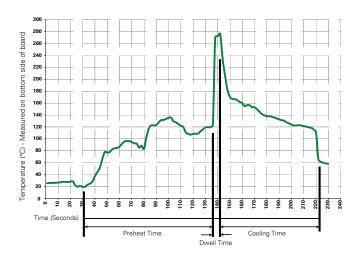
Reflow Co	ndition	Pb – Free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 secs	
Average ra (T _L) to pea	amp up rate (LiquidusTemp k	3°C/second max	
$T_{S(max)}$ to T_L	- Ramp-up Rate	5°C/second max	
D (1	-Temperature (T _L) (Liquidus)	217°C	
Reflow	-Temperature (t _L)	60 – 150 seconds	
PeakTemp	perature (T _P)	260 ^{+0/-5} °C	
Time with Temperatu	in 5°C of actual peak ure (t _p)	10 – 30 seconds	
Ramp-dov	vn Rate	6°C/second max	
Time 25°C	to peakTemperature (T _P)	8 minutes Max.	
Do not exe	ceed	260°C	



Soldering Parameters - Hand Soldering

Solder Iron Temperature: 350° C +/- 5°C Heating Time: 5 seconds max.

Soldering Parameters - Wave Soldering (Thru-Hole Devices)



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation		
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)		
Temperature Minimum:	100° C		
Temperature Maximum:	150° C		
Preheat Time:	60-180 seconds		
Solder Pot Temperature:	280° C Maximum		
Solder Dwell Time:	2-5 seconds		

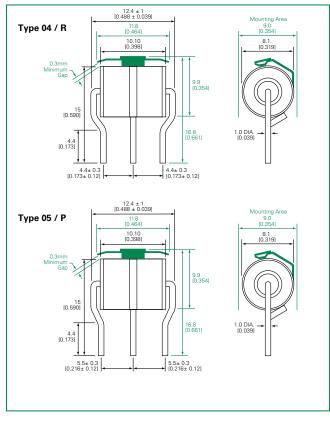
Note: Surge Arrestors with a Failsafe mechanism should be individually examined after soldering



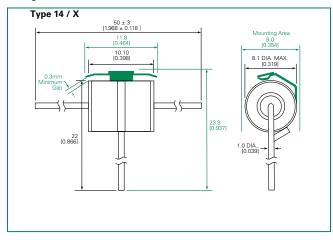
Device Dimensions

NOTE: Failsafe option dimensions shown in green.

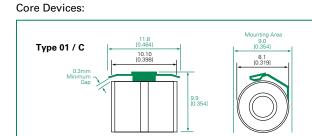
Shaped Radial Leaded Devices:



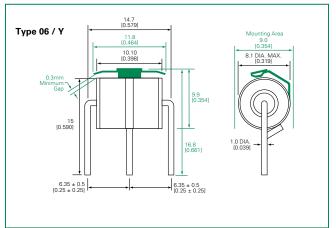
Straight "T" Leaded Devices:



Type "R" is available for SL1021B075 device only.

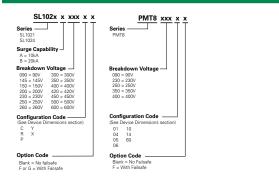


Straight Radial Leaded Devices:



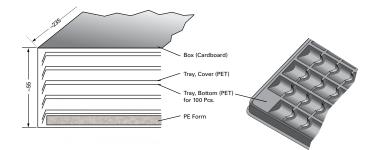


Part Numbering System and Ordering Information

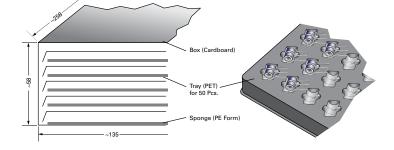


Packaging

For 'SL1021A/B' device type C, R, P, Y packing



For 'SL1021A/B' device type X packing



Device Type	Description	Quantity
Туре С	100pcs/tray x 5 trays per carton	500
Type R	100pcs/tray x 5 trays per carton	500
Type P	100pcs/tray x 5 trays per carton	500
Type Y	100pcs/tray x 5 trays per carton	500
Туре Х	50pcs/tray x 5 trays per carton	250

* Please contact the factory for further packaging information.